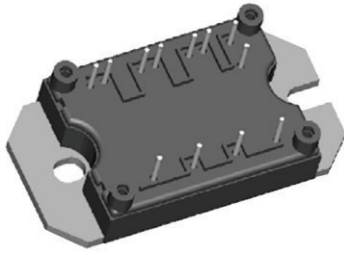



# “Half Bridge” IGBT MTP (Warp Speed IGBT), 114 A



MTP

## FEATURES

- Gen 4 warp speed IGBT technology
- HEXFRED® antiparallel diodes with ultrasoft reverse recovery
- Very low conduction and switching losses
- Optional SMD thermistor (NTC)
- Very low junction to case thermal resistance
- UL approved file E78996 
- Designed and qualified for industrial level
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


RoHS  
COMPLIANT

## PRIMARY CHARACTERISTICS

$V_{CES}$	600 V
$V_{CE(on)}$ typical at $V_{GE} = 15$ V	2.3 V
$I_C$ at $T_C = 25$ °C	114 A
Speed	30 kHz to 100 kHz
Package	MTP
Circuit configuration	Half bridge

## BENEFITS

- Optimized for welding, UPS and SMPS applications
- Low EMI, requires less snubbing
- Direct mounting to heatsink
- PCB solderable terminals
- Very low stray inductance design for high speed operation

## ABSOLUTE MAXIMUM RATINGS

PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		600	V
Continuous collector current	$I_C$	$T_C = 25$ °C	114	A
		$T_C = 109$ °C	50	
Pulsed collector current	$I_{CM}$		350	
Peak switching current	$I_{LM}$		350	
Diode continuous forward current	$I_F$	$T_C = 109$ °C	34	
Peak diode forward current	$I_{FM}$		200	
Gate to emitter voltage	$V_{GE}$		± 20	V
RMS isolation voltage	$V_{ISOL}$	Any terminal to case, $t = 1$ min	2500	
Maximum power dissipation	$P_D$	$T_C = 25$ °C	658	W
		$T_C = 100$ °C	263	

## ELECTRICAL SPECIFICATIONS ( $T_J = 25$ °C unless otherwise specified)

PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0$ V, $I_C = 500$ μA	600	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15$ V, $I_C = 50$ A	-	2.3	3.15	V
		$V_{GE} = 15$ V, $I_C = 100$ A	-	2.5	3.2	
		$V_{GE} = 15$ V, $I_C = 50$ A, $T_J = 150$ °C	-	1.72	2.17	
Gate threshold voltage	$V_{GE(th)}$	$I_C = 0.5$ mA	3	-	6	
Collector to emitter leaking current	$I_{CES}$	$V_{GE} = 0$ V, $I_C = 600$ A	-	-	0.4	mA
		$V_{GE} = 0$ V, $I_C = 600$ A, $T_J = 150$ °C	-	-	10	
Diode forward voltage drop	$V_{FM}$	$I_F = 50$ A, $V_{GE} = 0$ V	-	1.58	1.80	V
		$I_F = 50$ A, $V_{GE} = 0$ V, $T_J = 150$ °C	-	1.49	1.68	
		$I_F = 100$ A, $V_{GE} = 0$ V, $T_J = 25$ °C	-	1.9	2.17	
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = \pm 20$ V	-	-	± 250	nA



SWITCHING CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Total gate charge (turn-on)	Q <sub>g</sub>	I <sub>C</sub> = 52 A V <sub>CC</sub> = 400 V V <sub>GE</sub> = 15 V	-	331	385	nC
Gate to emitter charge (turn-on)	Q <sub>ge</sub>		-	44	52	
Gate to collector charge (turn-on)	Q <sub>gc</sub>		-	133	176	
Turn-on switching loss	E <sub>on</sub>	Internal gate resistors (see electrical diagram) I <sub>C</sub> = 50 A, V <sub>CC</sub> = 480 V, V <sub>GE</sub> = 15 V, L = 200 μH energy losses include tail and diode reverse recovery, T <sub>J</sub> = 25 °C	-	0.26	-	mJ
Turn-off switching loss	E <sub>off</sub>		-	1.2	-	
Total switching loss	E <sub>ts</sub>		-	1.46	-	
Turn-on switching loss	E <sub>on</sub>	Internal gate resistors (see electrical diagram) I <sub>C</sub> = 50 A, V <sub>CC</sub> = 480 V, V <sub>GE</sub> = 15 V, L = 200 μH energy losses include tail and diode reverse recovery, T <sub>J</sub> = 150 °C	-	0.73	-	mJ
Turn-off switching loss	E <sub>off</sub>		-	1.66	-	
Total switching loss	E <sub>ts</sub>		-	2.39	-	
Input capacitance	C <sub>ies</sub>	V <sub>GE</sub> = 0 V V <sub>CC</sub> = 30 V f = 1.0 MHz	-	7100	-	pF
Output capacitance	C <sub>oes</sub>		-	510	-	
Reverse transfer capacitance	C <sub>res</sub>		-	140	-	
Diode reverse recovery time	t <sub>rr</sub>	V <sub>CC</sub> = 200 V, I <sub>C</sub> = 50 A dI/dt = 200 A/μs	-	82	97	ns
Diode peak reverse current	I <sub>rr</sub>		-	8.3	10.6	A
Diode recovery charge	Q <sub>rr</sub>		-	340	514	nC
Diode reverse recovery time	t <sub>rr</sub>	V <sub>CC</sub> = 200 V, I <sub>C</sub> = 50 A dI/dt = 200 A/μs T <sub>J</sub> = 125 °C	-	137	153	ns
Diode peak reverse current	I <sub>rr</sub>		-	12.7	14.8	A
Diode recovery charge	Q <sub>rr</sub>		-	870	1132	nC

THERMISTOR SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Resistance	R <sub>0</sub> <sup>(1)</sup>	T <sub>0</sub> = 25 °C	-	30	-	kΩ
Sensitivity index of the thermistor material	β <sup>(1)(2)</sup>	T <sub>0</sub> = 25 °C T <sub>1</sub> = 85 °C	-	4000	-	K

**Notes**

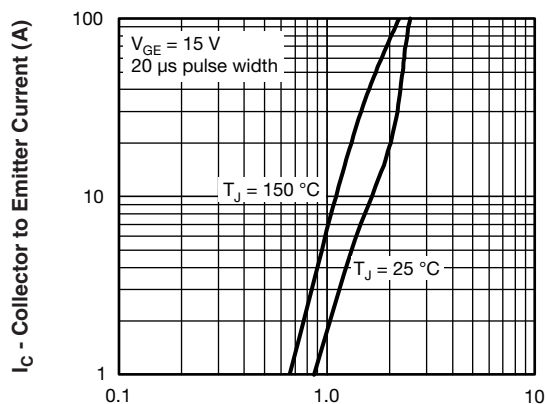
<sup>(1)</sup> T<sub>0</sub>, T<sub>1</sub> are thermistor's temperatures

<sup>(2)</sup>  $\frac{R_0}{R_1} = \exp\left[\beta\left(\frac{1}{T_0} - \frac{1}{T_1}\right)\right]$ , temperature in Kelvin

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Operating junction temperature range	T <sub>J</sub>	IGBT, diode	-40	-	150	°C
		Thermistor	-40	-	125	
Storage temperature range	T <sub>Stg</sub>		-40	-	125	
Junction to case	R <sub>thJC</sub>	IGBT	-	-	0.38	°C/W
		Diode	-	-	0.8	
Case to sink per module	R <sub>thCS</sub>	Heatsink compound thermal conductivity = 1 W/mK	-	0.06	-	
Clearance <sup>(1)</sup>		External shortest distance in air between 2 terminals	5.5	-	-	mm
Creepage <sup>(1)</sup>		Shortest distance along the external surface of the insulating material between 2 terminals	8	-	-	
Mounting torque to heatsink		A mounting compound is recommended and the torque should be checked after 3 hours to allow for the spread of the compound. Lubricated threads.	3 ± 10 %			Nm
Weight			66			g

**Note**

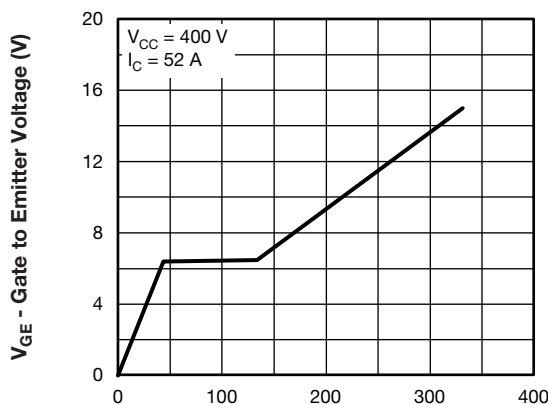
<sup>(1)</sup> Standard version only i.e. without optional thermistor



94468\_01

$V_{CE}$  - Collector to Emitter Voltage (V)

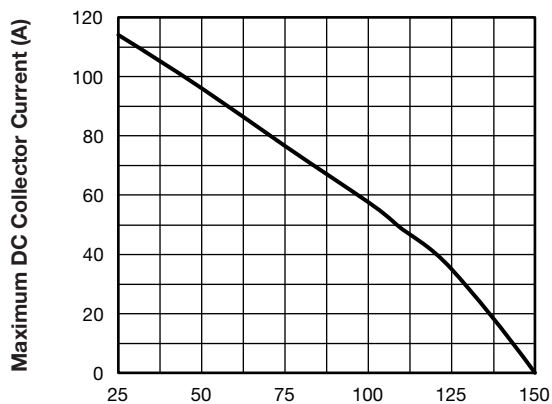
Fig. 1 - Typical Output Characteristics



94468\_04

$Q_G$  - Typical Gate Charge (nC)

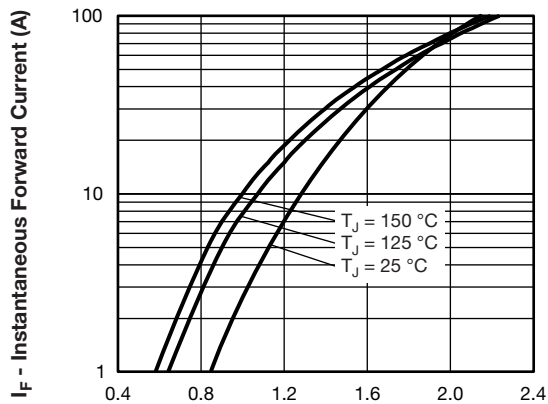
Fig. 4 - Typical Gate Charge vs. Gate to Emitter Voltage



94468\_02

$T_C$  - Case Temperature (°C)

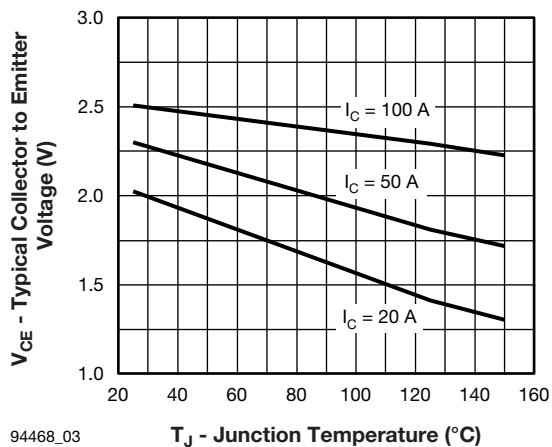
Fig. 2 - Maximum Collector Current vs. Case Temperature



94468\_05

$V_{FM}$  - Forward Voltage Drop (V)

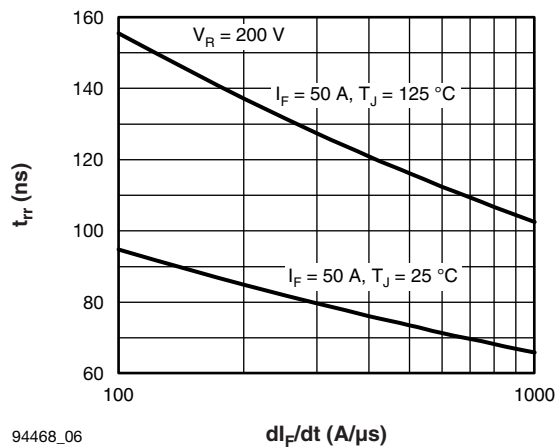
Fig. 5 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current



94468\_03

$T_J$  - Junction Temperature (°C)

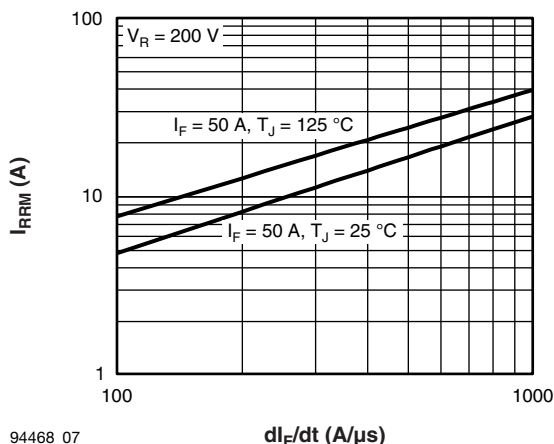
Fig. 3 - Typical Collector to Emitter Voltage vs. Junction Temperature



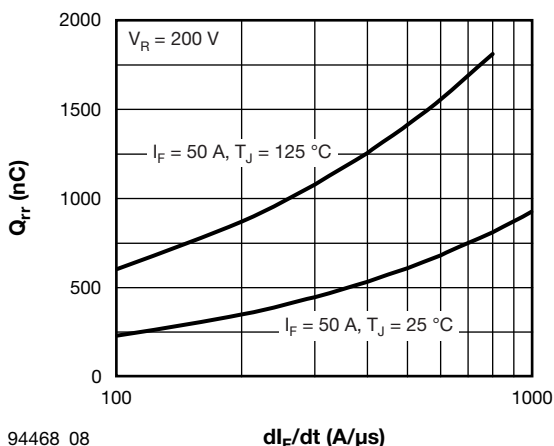
94468\_06

$dI_F/dt$  (A/μs)

Fig. 6 - Typical Reverse Recovery Time vs.  $dI_F/dt$



94468\_07

Fig. 7 - Typical Reverse Recovery Current vs.  $dI_F/dt$ 


94468\_08

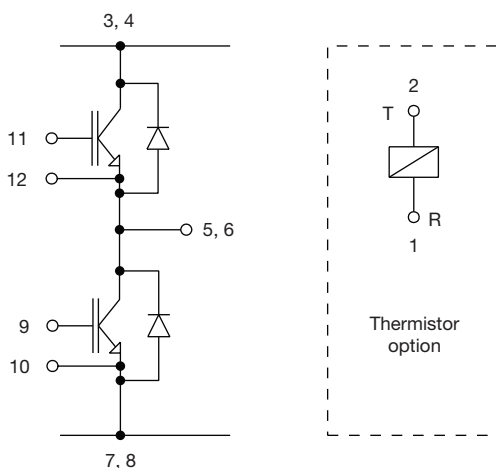
Fig. 8 - Typical Stored Charge vs.  $dI_F/dt$ 


Fig. 9 - Functional Diagram

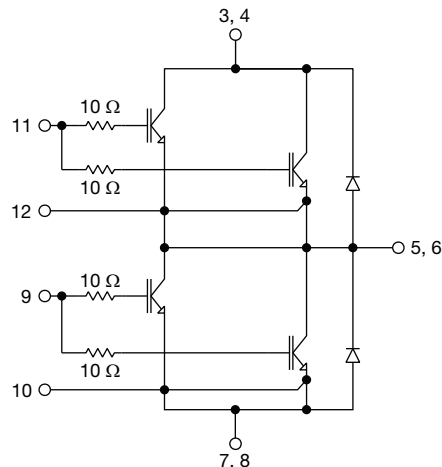


Fig. 10 - Electrical Diagram

## ORDERING INFORMATION TABLE

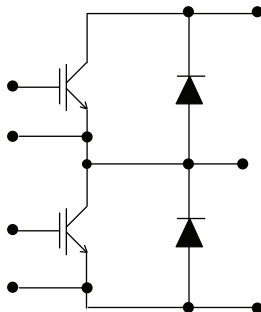
Device code

VS-	50	MT	060	W	H	T	A	PbF
1	2	3	4	5	6	7	8	9

1	-	Vishay Semiconductors product
2	-	Current rating (50 = 50 A)
3	-	Essential part number
4	-	Voltage rating (060 = 600 V)
5	-	Speed / type (W = warp IGBT)
6	-	Circuit configuration (H = half bridge)
7	-	T = thermistor
8	-	A = Al <sub>2</sub> O <sub>3</sub> substrate
9	-	Lead (Pb)-free



## CIRCUIT CONFIGURATION

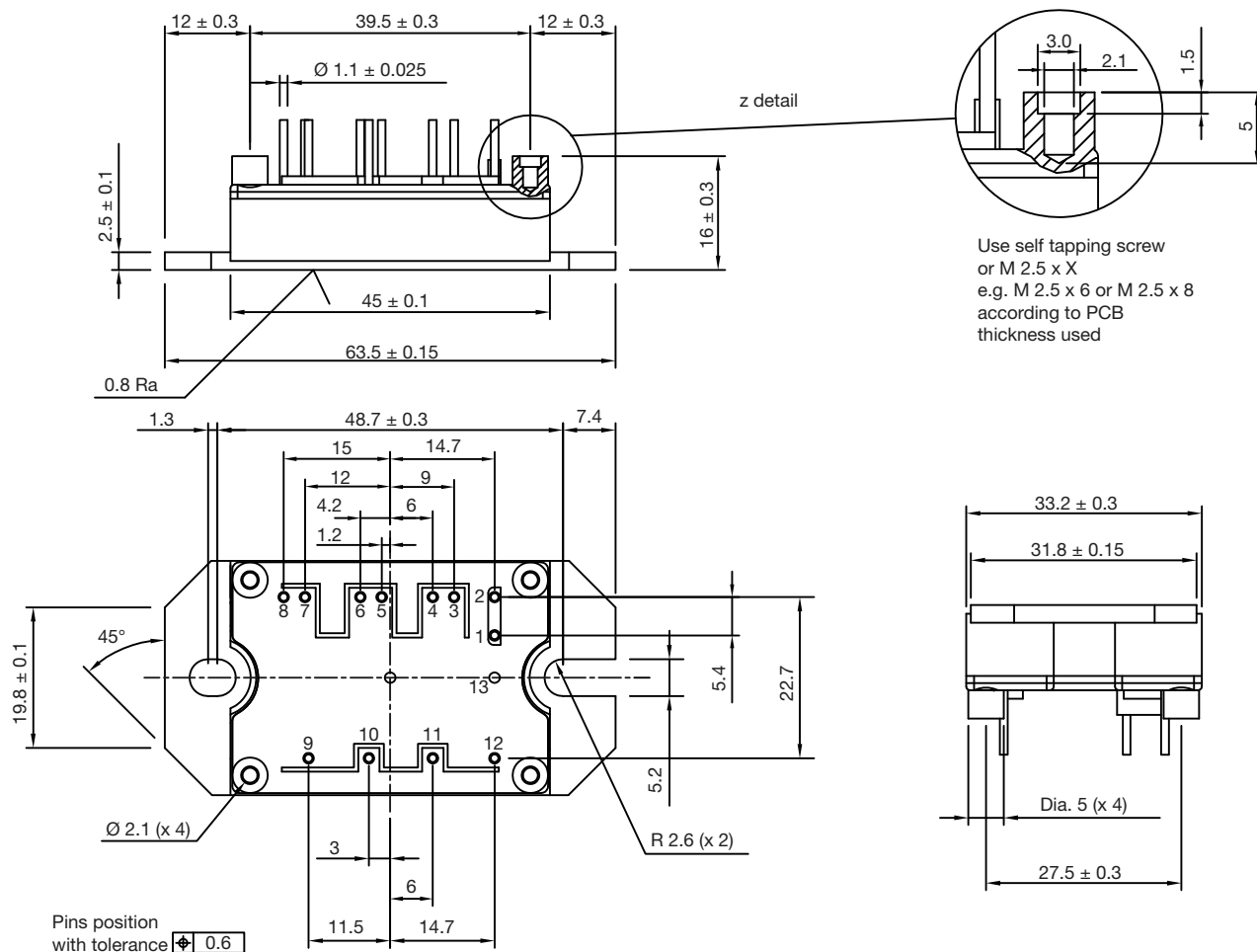


## LINKS TO RELATED DOCUMENTS

Dimensions	<a href="http://www.vishay.com/doc?95175">www.vishay.com/doc?95175</a>
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# MTP

**DIMENSIONS** in millimeters



### Note

- Unused terminals are not assembled in the package



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